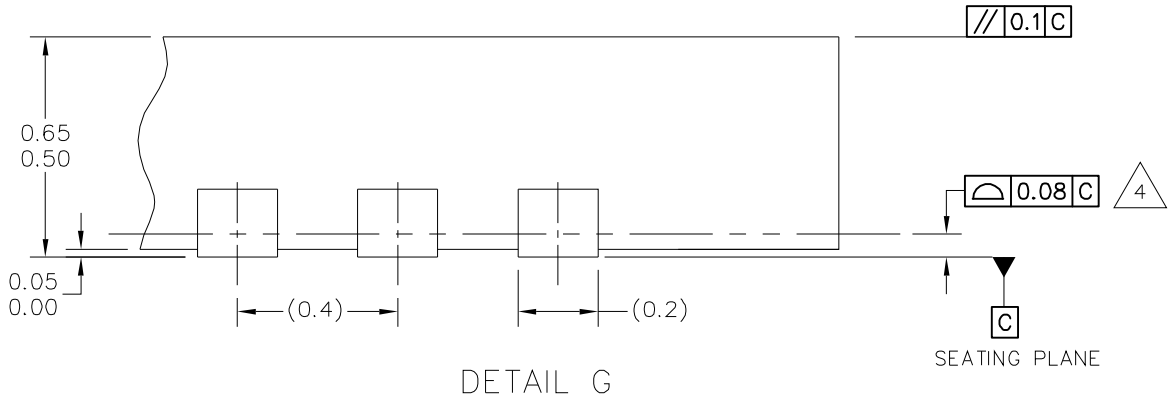



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TITLE: THERMALLY ENHANCED QUAD FLAT NO LEAD PACKAGE (QFN) 20 TERMINAL, 0.4 PITCH (3 X 3 X 0.65)	DOCUMENT NO: 98ASA00037D REV: B	
	STANDARD: NON JEDEC	
	SOT1582-1 05 JAN 2016	



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		STANDARD: NON JEDEC	
		SOT1582-1	05 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. THIS IS NON JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND ALL OTHER BOTTOM SURFACE METALLIZATION.
5. DELETED.

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